GSM6320XF

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Preliminary Specification

60V N-Channel MOSFET

Absolute Maximum Ratings (T_A=25°C unless otherwise specified)

Symbol	Parameter		Value	Unit	
V _{DS}	Drain-Source Voltage		60	V	
V _{GS}	Gate-Source Voltage		±20	V	
	Continuous Drain Current (Silicon Limited)	T _C =25°C	168		
lp		T _C =100°C	106	A	
	Continuous Drain Current (Package Limited)		100		
Ірм	Pulsed Drain Current ¹		400	Α	
	Power Dissipation	T _C =25°C	125	100	
P _D		T _C =100°C	50	W	
R _{eJC}	Thermal Resistance-Junction to Case		1	°C/W	
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient		62	°C/W	
TJ	Operating Junction Temperature Range		-55 to +150	$^{\circ}$ C	
Тѕтс	Storage Temperature Range		-55 to +150	$^{\circ}$ C	

NOTE:

Electrical Characteristics (T_A=25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
	Static						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	60			V	
IDSS	Drain-Source Leakage Current	V _{DS} =60V, V _{GS} =0V			1	uA	
Igss	Gate-Source Leakage Current	V _{DS} =0V, V _{GS} =±20V			±100	nA	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1.2		2.5	V	
R _{DS(on)}	Dunin Course On Besistense	V _{GS} =10V, I _D =20A			2.1		
	Drain-Source On-Resistance	V _{GS} =4.5V, I _D =10A			3.2	mΩ	
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =1A			1.0	V	



^{1.} Pulse width limited by maximum junction temperature.

Packages & Pin Assignments

DFN5X6-8L				Equivalent	Circuit
	1 2 3 4		G S		
Pin	Symbol	Description	Pin	Symbol	Description
1	S	Source	8	D	Drain
2	S	Source	7	D	Drain
3	S	Source	6	D	Drain
4	G	Gate	5	D	Drain



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